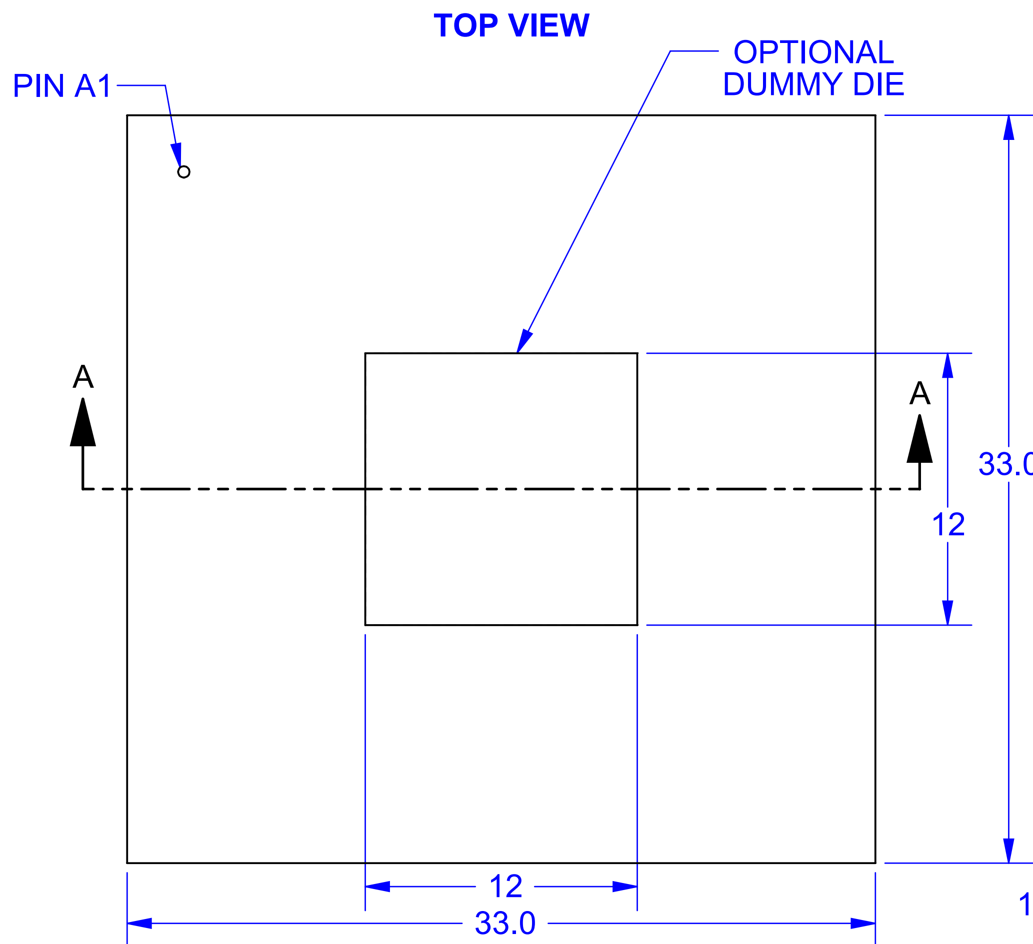
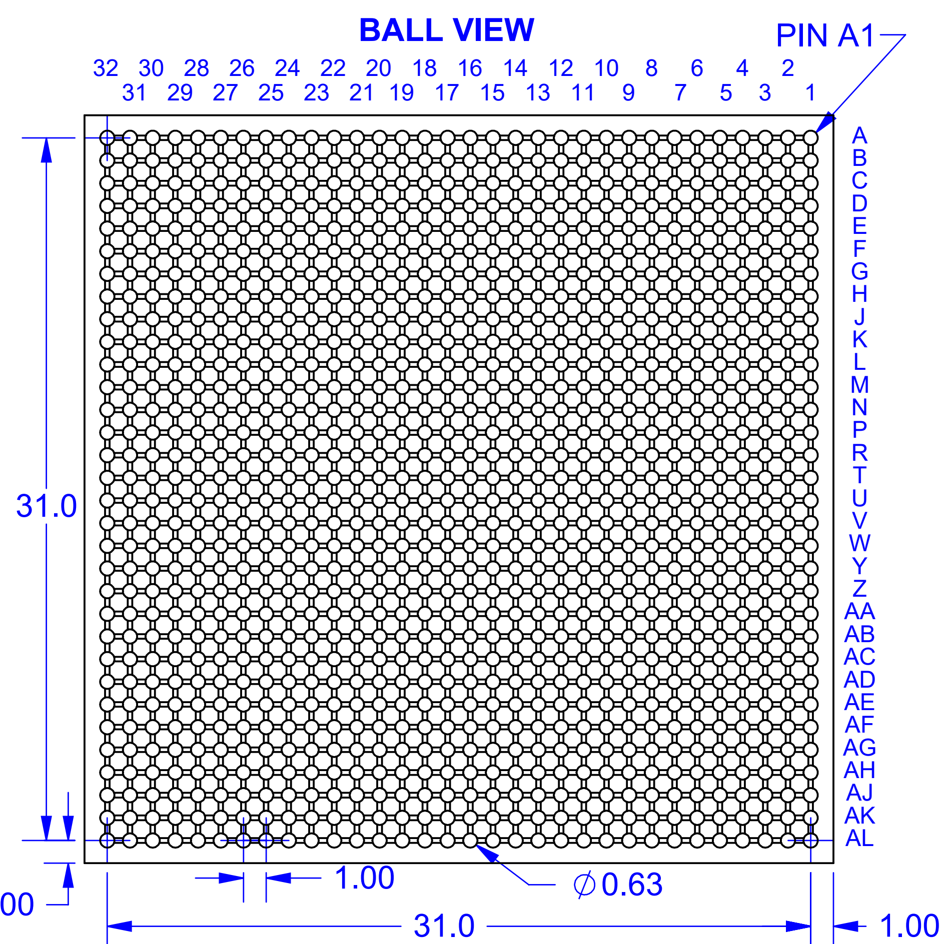
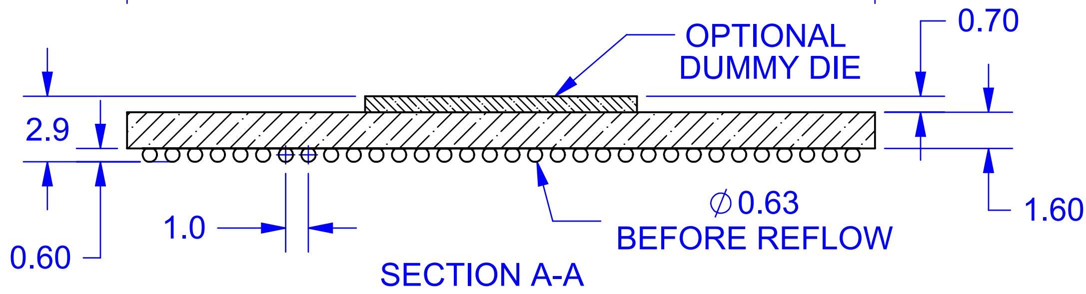




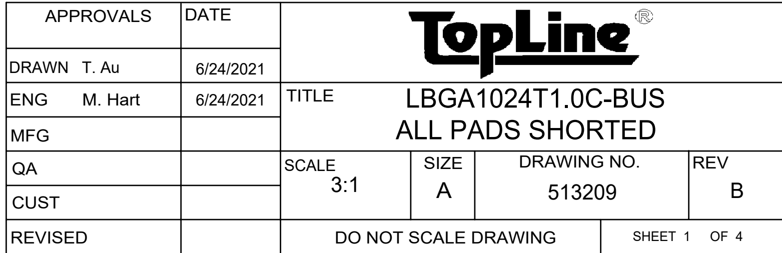


Notes: (Unless Otherwise Specified).
1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.635mm [25 MIL].
4) SOLDER MASK DEFINED PAD OPENING: 0.508mm [20 MIL].
5) PAD Cu DIAMETER: 0.685mm [27 MIL].
6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
7) DUMMY DIE IS OPTIONAL.
8) DAISY CHAIN PATTERN (SEE PAGE 2).
9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

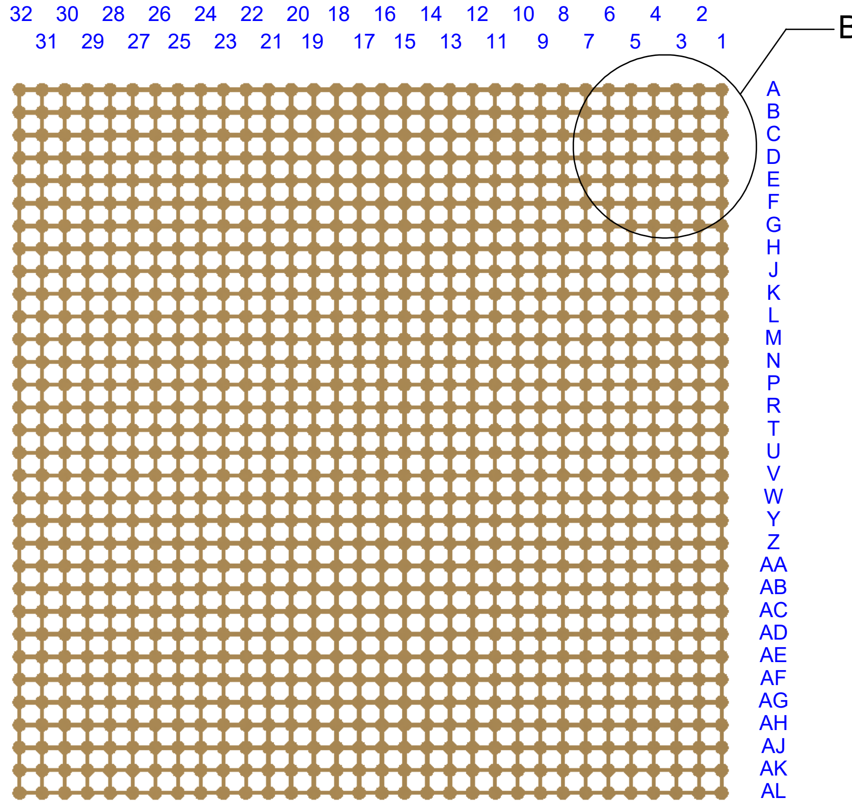
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA1024T1.0C-BUS	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA1024T1.0C-BUS-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA1024T1.0-BUS	Sn63/Pb37	NO	NO	NO
LBGA1024T1.0-BUS-D	Sn63/Pb37	NO	NO	YES

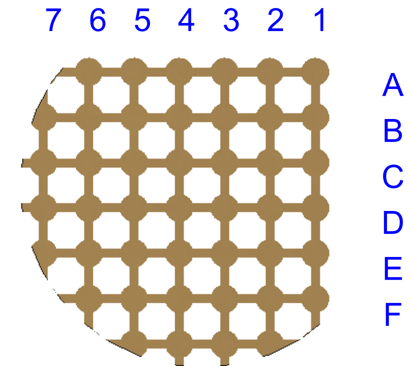
x



APPROVALS	DATE	TopLine®
DRAWN T. Au	6/24/2021	
ENG M. Hart	6/24/2021	TITLE LBGA1024T1.0C-BUS ALL PADS SHORTED
MFG		
QA		SCALE 3:1 / SIZE A / DRAWING NO. 513209 / REV B
CUST		
REVISED		DO NOT SCALE DRAWING / SHEET 1 OF 4

BALL VIEW





DETAIL B
SCALE 6 : 1

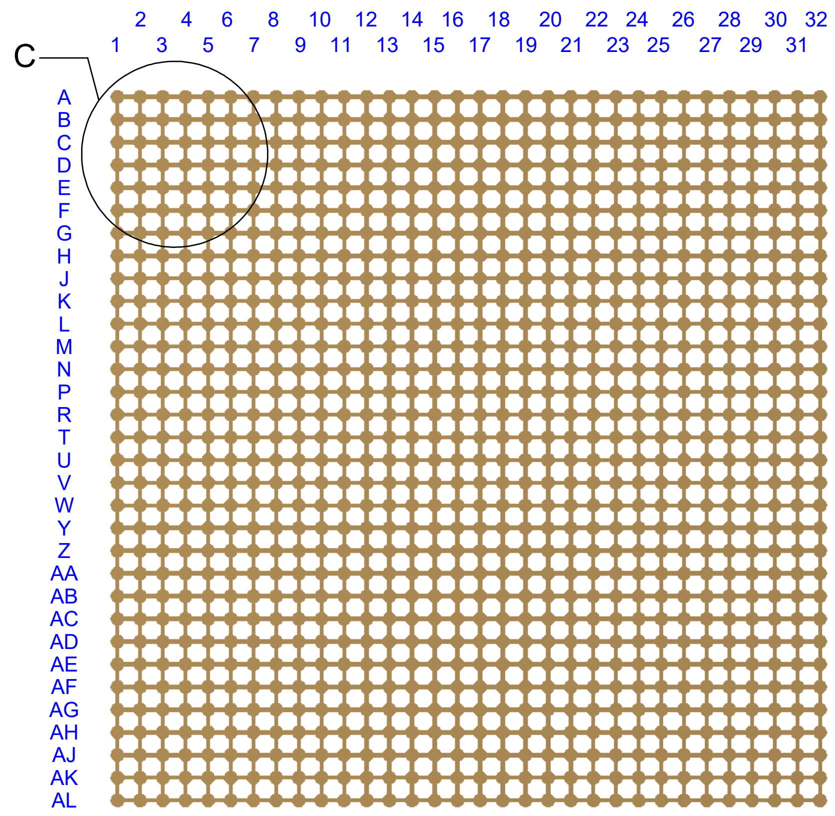
ALL PADS CONNECTED

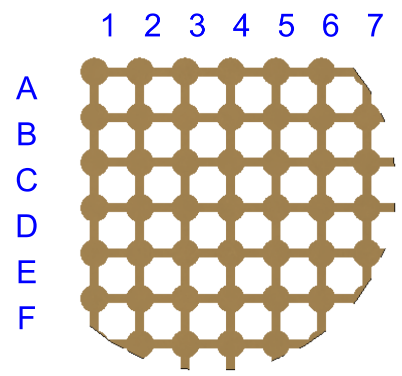
Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER 0.685mm [27 MIL].
3) PCB DAISY CHAIN TRACING LINE WIDTH 0.204mm [8 MIL].
4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.508mm [20 MIL].

TopLine®

TITLE	LBGA1024T1.0C-BUS ALL PADS SHORTED		
SCALE 3:1	SIZE A	DRAWING NO. 513209	REV B
DO NOT SCALE DRAWING		SHEET 2 OF 4	

BOTTOM SIDE (TOP X-RAY VIEW)





DETAIL C
SCALE 6 : 1

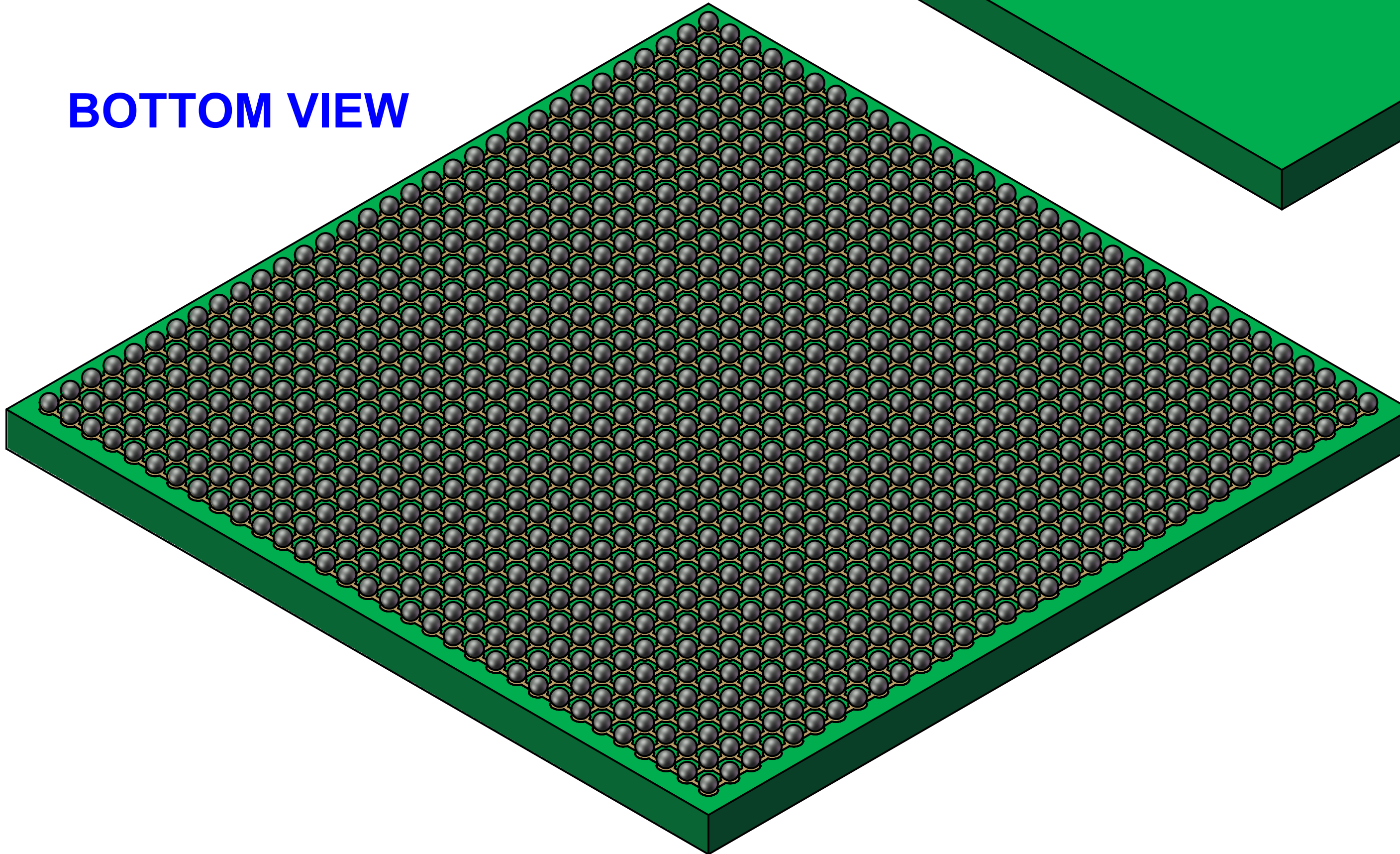
ALL PADS
CONNECTED

TopLine®			
TITLE LBGA1024T1.0C-BUS ALL PADS SHORTED			
SCALE 3:1	SIZE A	DRAWING NO. 513209	REV B
DO NOT SCALE DRAWING		SHEET 3 OF 4	

MODEL

TOP VIEW
WITH DUMMY DIE

BOTTOM VIEW



TopLine®			
TITLE LBGA1024T1.0C-BUS ALL PADS SHORTED			
SCALE 2:1	SIZE A	DRAWING NO. 513209	REV B
DO NOT SCALE DRAWING		SHEET 4 OF 4	